



## Statement of Compliance

### Requested Part

12 April 2013

201046-2

(Part 1 of 1)

### SERIES "M" MIN RECT GUIDE PIN

Part Status: Superseded

EU RoHS/ELV Code: Always EU RoHS/ELV Compliant

Solder Process Capability Code: Not applicable for solder process capability

China RoHS:  No Restricted Materials Above Threshold

Exemptions: No Substance>Threshold

REACH Oct 2008 SvHC Compliance: Contains no REACH October 2008 SvHC(s)

REACH Jan/Mar 2010 SvHC Compliance: Contains no REACH Jan/Mar 2010 SvHC(s)

REACH June 2010 SvHC Compliance: Contains no REACH June 2010 SvHC(s)

REACH Dec 2010 SvHC Compliance: Contains no REACH December 2010 SvHC(s)

REACH June 2011 SvHC Compliance: Contains no REACH June 2011 SvHC(s)

REACH December 2011 SvHC Compliance: Contains no REACH December 2011 SvHC(s)

REACH June 2012 SvHC Compliance: Contains no REACH June 2012 SvHC(s)

REACH December 2012 SvHC Compliance: Contains no REACH December 2012 SvHC(s)

Halogen Content: Not Yet Reviewed for halogen content

David R. Bender

Director, Product Compliance

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The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hex chrome, mercury, PBB, PBDE, and 0.01% for cadmium, or qualify for an exemption to above limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Note that any exemptions taken in this case would not include application specific exemptions (e.g. lead in solder for servers) as TE cannot determine where component products will be used.

Additionally, the part numbers that are identified as 5 of 6 compliant meet the material limits described above, except that these products have lead in the solderable interface only. These products may be suitable for use in an application that has an exemption for the use of lead in solder (e.g. servers, network infrastructure, etc).

Finished electrical and electronic products will be CE marked as required by Directive 2011/65/EU (RoHS2). Components may not be CE marked.

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information provided by our suppliers. This information is subject to change.




**RoHS Equivalent Part(s) for Part 201046-2**

12 April 2013

**1-201046-2**

(Equivalent Part 1 of 1)

**SERIES "M" MIN RECT GUIDE PIN**

Part Status: Active  
EU RoHS/ELV Code: Always EU RoHS/ELV Compliant  
Solder Process Capability Code: Not applicable for solder process capability  
China RoHS:  No Restricted Materials Above Threshold  
Exemptions: No Substance>Threshold  
REACH Oct 2008 SvHC Compliance: Contains no REACH October 2008 SvHC(s)  
REACH Jan/Mar 2010 SvHC Compliance: Contains no REACH Jan/Mar 2010 SvHC(s)  
REACH June 2010 SvHC Compliance: Contains no REACH June 2010 SvHC(s)  
REACH Dec 2010 SvHC Compliance: Contains no REACH December 2010 SvHC(s)  
REACH June 2011 SvHC Compliance: Contains no REACH June 2011 SvHC(s)  
REACH December 2011 SvHC Compliance: Contains no REACH December 2011 SvHC(s)  
REACH June 2012 SvHC Compliance: Contains no REACH June 2012 SvHC(s)  
REACH December 2012 SvHC Compliance: Contains no REACH December 2012 SvHC(s)  
Halogen Content: Not Yet Reviewed for halogen content  
Description of Difference: RoHS compliant part

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